

APPLICATIONS

- ✓ Ethernet - 10/100 Base T
- ✓ Cellular Phones
- ✓ Audio & Video Inputs
- ✓ FireWire, SCSI & USB Interfaces

IEC COMPATIBILITY (EN61000-4)

- ✓ 61000-4-2 (ESD): Air - 15kV, Contact - 8kV
- ✓ 61000-4-4 (EFT): 40A - 5/50ns
- ✓ 61000-4-5 (Surge): 12A, 8/20 μ s - Level 1(Line-Gnd) & Level 2(Line-Line)

FEATURES

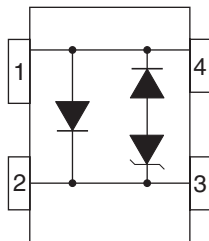
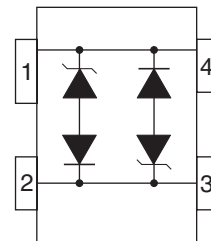
- ✓ 350 Watts Peak Pulse Power per Line (tp=8/20 μ s)
- ✓ Unidirectional & Bidirectional Configurations
- ✓ Available in Multiple Voltage Types Ranging From 3V to 24V
- ✓ Protects One Line
- ✓ ESD Protection > 40 kilovolts
- ✓ Low Clamping Voltage
- ✓ Low Capacitance: 5pF
- ✓ RoHS Compliant

MECHANICAL CHARACTERISTICS

- ✓ Molded JEDEC SOT-143 Package
- ✓ Weight 9 milligrams (Approximate)
- ✓ Available in Lead-Free Pure-Tin Plating(Annealed)
- ✓ Solder Reflow Temperature:
Pure-Tin - Sn, 100: 260-270°C
- ✓ Consult Factory for Leaded Device Availability
- ✓ Flammability Rating UL 94V-0
- ✓ 8mm Tape and Reel Per EIA Standard 481
- ✓ Marking: Marking Code



PIN CONFIGURATIONS

UNIDIRECTIONAL

BIDIRECTIONAL


PSLC03 thru PSLC24C

DEVICE CHARACTERISTICS

MAXIMUM RATINGS @ 25°C Unless Otherwise Specified

PARAMETER	SYMBOL	VALUE	UNITS
Peak Pulse Power ($t_p = 8/20\mu s$) - See Figure 1	P_{PP}	350	Watts
Operating Temperature	T_L	-55 to 150	°C
Storage Temperature	T_{STG}	-55 to 150	°C

ELECTRICAL CHARACTERISTICS PER LINE @ 25°C Unless Otherwise Specified

PART NUMBER (See Notes 1-2)	DEVICE MARKING	RATED STAND-OFF VOLTAGE V_{WM} VOLTS	MINIMUM BREAKDOWN VOLTAGE @ 1mA $V_{(BR)}$ VOLTS	MAXIMUM CLAMPING VOLTAGE (See Fig. 2) @ $I_p = 5A$ V_C VOLTS	MAXIMUM CLAMPING VOLTAGE (See Fig. 2) @ 8/20 μs $V_C @ I_{PP}$	MAXIMUM LEAKAGE CURRENT @ V_{WM} I_b μA	TYPICAL CAPACITANCE 0V @ 1 MHz C pF
PSLC03	3U	3.3	4.0	9.0	19.0V @ 20.0A	125	5
PSLC03C	3B	3.3	4.0	9.0	19.0V @ 20.0A	125	5
PSLC05	5U	5.0	6.0	11.0	18.3V @ 17.0A	20	5
PSLC05C	5B	5.0	6.0	11.0	18.3V @ 17.0A	20	5
PSLC08	8U	8.0	8.5	16.6	18.5V @ 17.0A	10	5
PSLC08C	8B	8.0	8.5	16.6	18.5V @ 17.0A	10	5
PSLC12	12U	12.0	13.3	24.0	28.6V @ 11.0A	1	5
PSLC12C	12B	12.0	13.3	24.0	28.6V @ 11.0A	1	5
PSLC15	15U	15.0	16.6	30.0	31.8V @ 10.0A	1	5
PSLC15C	15B	15.0	16.6	30.0	31.8V @ 10.0A	1	5
PSLC24	24U	24.0	26.7	N/A	56.0V @ 6.0A	1	5
PSLC24C	24B	24.0	26.7	N/A	56.0V @ 6.0A	1	5

Note 1: Part numbers with an additional "C" suffix are bidirectional devices, i.e., PSLC05C.

Note 2: *Unidirectional Only:* Positive potential is applied from pin 2 to 1 or pin 3 to 4.

FIGURE 1
PEAK PULSE POWER VS PULSE TIME

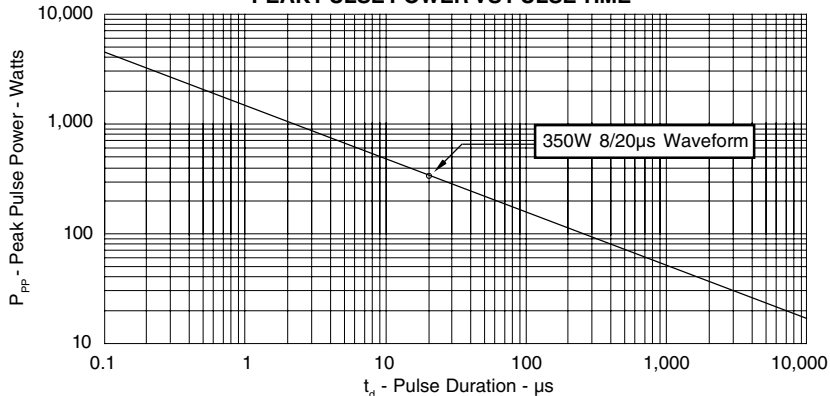
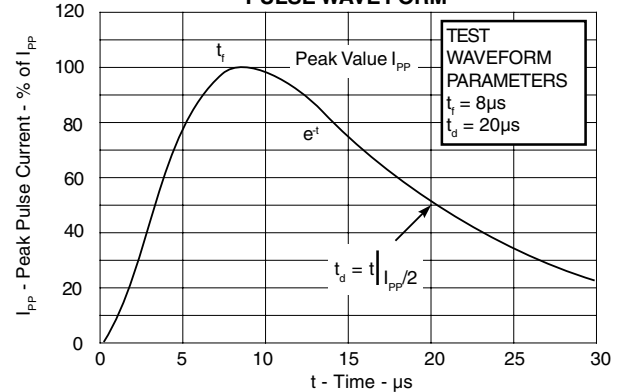
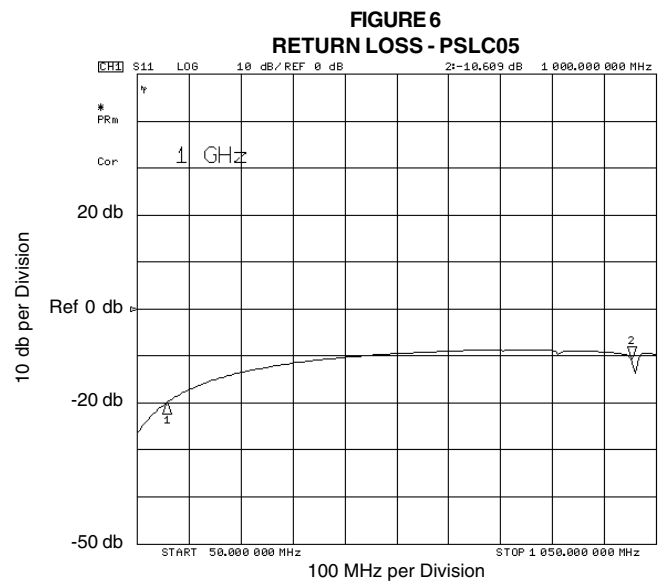
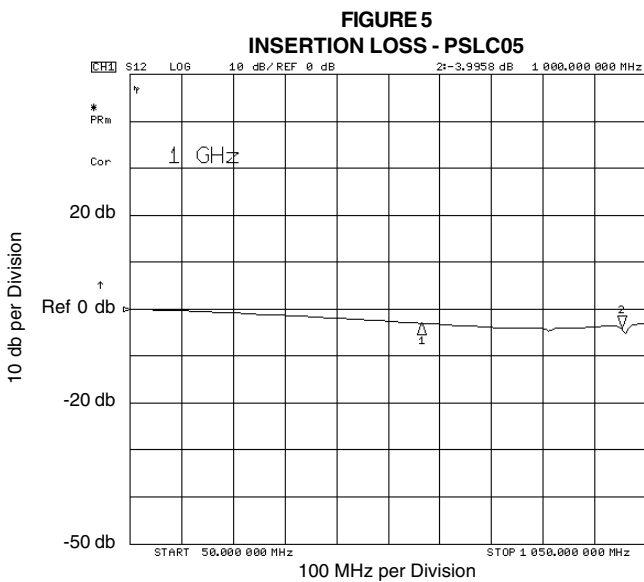
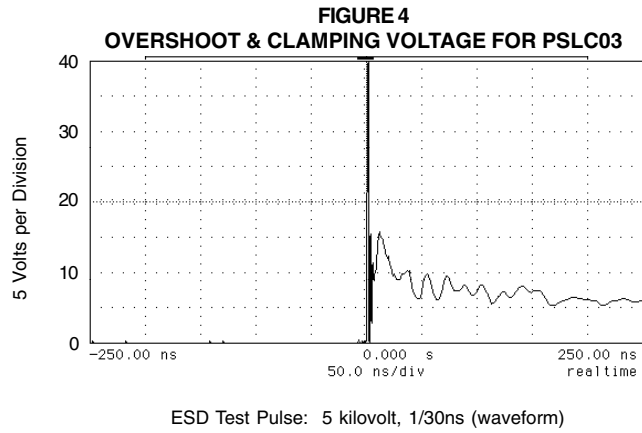
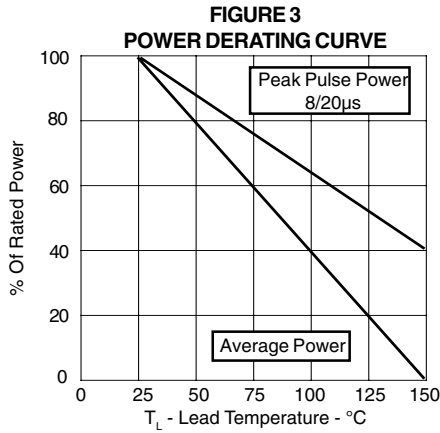


FIGURE 2
PULSE WAVE FORM



GRAPHS



APPLICATIONS

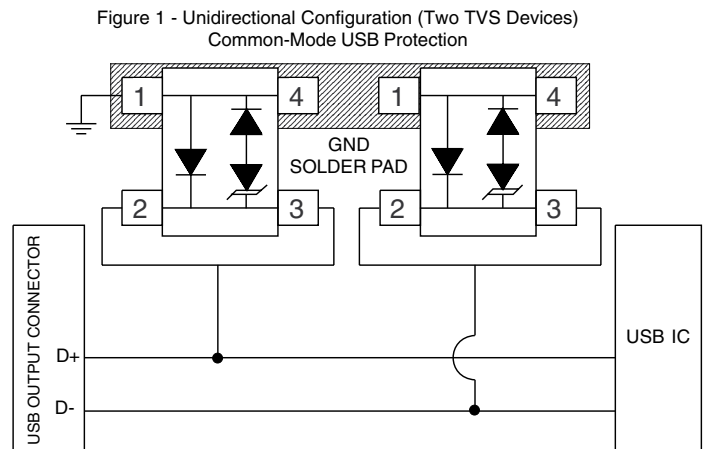
The PSLC Series are TVS arrays designed to protect I/O or data lines from the damaging effects of ESD and EFT. This product series provides both unidirectional and bidirectional protection, with a surge capability of 500 Watts P_{pp} per line for an 8/20 μ s waveform and ESD protection > 40kV.

UNIDIRECTIONAL COMMON-MODE CONFIGURATION (Figure 1)

The two PSLC Series devices provide protection in a common-mode configuration as depicted in Figure 1.

Circuit connectivity is as follows:

- ✓ TVS Device 1: Line 1 (D+) is connected to Pins 2 & 3.
- ✓ TVS Device 2: Line 2 (D-) is connected to Pins 2 & 3.
- ✓ Both TVS Devices: Pins 1 & 4 connected to ground.



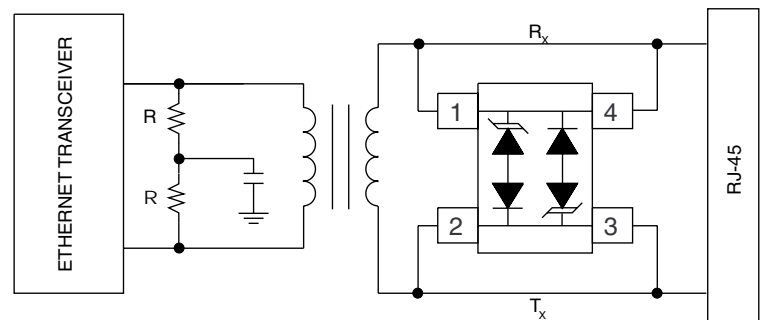
BIDIRECTIONAL DIFFERENTIAL-MODE CONFIGURATION (Figure 2)

The PSLCxxC Series provides protection in a differential-mode configuration as depicted in Figure 2.

Circuit connectivity is as follows:

- ✓ Line 1 (R_x) is connected to Pins 1 & 4.
- ✓ Line 2 (T_x) is connected to Pins 2 & 3.

Figure 2 - Bidirectional Configuration
Differential-Mode Ethernet Protection



CIRCUIT BOARD LAYOUT RECOMMENDATIONS

Circuit board layout is critical for Electromagnetic Compatibility (EMC) protection. The following guidelines are recommended:

- ✓ The protection device should be placed near the input terminals or connectors, the device will divert the transient current immediately before it can be coupled into the nearby traces.
- ✓ The path length between the TVS device and the protected line should be minimized.
- ✓ All conductive loops including power and ground loops should be minimized.
- ✓ The transient current return path to ground should be kept as short as possible to reduce parasitic inductance.
- ✓ Ground planes should be used whenever possible. For multilayer PCBs, use ground vias.

PSLC03 thru PSLC24C

SOT-143 PACKAGE OUTLINE & DIMENSIONS

PACKAGE OUTLINE		SOT-143			
PACKAGE DIMENSIONS					
DIM	MILLIMETERS		INCHES		
	MIN	MAX	MIN	MAX	
A	2.80	3.04	0.110	0.120	
B	1.20	1.39	0.047	0.055	
C	0.84	1.14	0.033	0.045	
D	0.39	0.50	0.015	0.020	
F	0.79	0.93	0.031	0.037	
G	1.78	2.03	0.070	0.080	
H	0.013	0.10	0.0005	0.004	
J	0.08	0.15	0.003	0.006	
K	0.46	0.60	0.018	0.024	
L	0.445	0.60	0.0175	0.024	
L1	0.40	0.60	0.016	0.024	
R	0.72	0.83	0.028	0.033	
S	2.11	2.48	0.083	0.098	

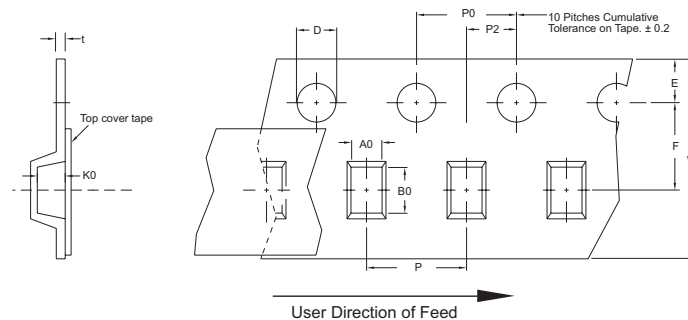
MOUNTING PAD																				
<table border="1" style="margin: auto;"> <thead> <tr> <th colspan="3">TYPICAL</th> </tr> <tr> <th>DIM</th> <th>Millimeters</th> <th>Inches</th> </tr> </thead> <tbody> <tr> <td>X</td> <td>1.2 x 0.9</td> <td>0.047 x 0.035</td> </tr> <tr> <td>Yx3</td> <td>0.85 x 0.85</td> <td>0.033 x 0.033</td> </tr> <tr> <td>m</td> <td>2.0</td> <td>0.079</td> </tr> <tr> <td>n</td> <td>1.9</td> <td>0.075</td> </tr> </tbody> </table>			TYPICAL			DIM	Millimeters	Inches	X	1.2 x 0.9	0.047 x 0.035	Yx3	0.85 x 0.85	0.033 x 0.033	m	2.0	0.079	n	1.9	0.075
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NOTES				
1. Dimensioning and tolerances per ANSI Y14.5M, 1985.				
2. Controlling Dimension: Inches				
3. Dimensions are exclusive of mold flash and metal burrs.				
TAPE & REEL ORDERING NOMENCLATURE				
1. Surface mount product is taped and reeled in accordance with EIA-481.				
2. Suffix -T7 = 7 Inch Reel - 3,000 pieces per 8mm tape, i.e., PSLC05C-T7.				
3. Suffix -T13 = 13 Inch Reel - 10,000 pieces per 8mm tape, i.e., PSLC05C-T13.				
4. Suffix -LF = Lead-Free, Pure-Tin Plating, i.e., PSLC05C-LF-T7.				

Outline & Dimensions: Rev 3 - 3/08, 06011

Tape & Reel Specifications (Dimensions in millimeters)

Reel Dia.	Tape Width	A0	B0	K0	D	E	F	W	P0	P2	P	tmax
178mm (7")	8mm	3.10 ± 0.10	2.70 ± 0.10	1.35 ± 0.10	1.50 ± 0.10	1.75 ± 0.10	3.50 ± 0.05	8.00 ± 0.30	4.00 ± 0.10	2.00 ± 0.05	4.00 ± 0.10	0.25



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ProTek Devices
 2929 South Fair Lane, Tempe, AZ 85282
 Tel: 602-431-8101 Fax: 602-431-2288
 E-Mail: sales@protekdevices.com
 Web Site: www.protekdevices.com